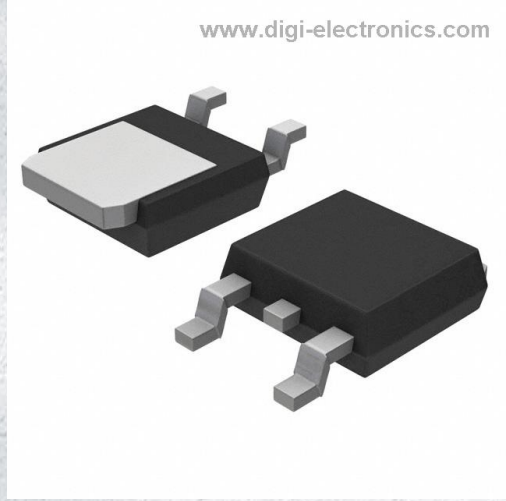
MJD210RLG Datasheet



https://www.DiGi-Electronics.com

DiGi Electronics Part Number	MJD210RLG-DG
Manufacturer	onsemi
Manufacturer Product Number	MJD210RLG
Description	TRANS PNP 25V 5A DPAK
Detailed Description	Bipolar (BJT) Transistor PNP 25 V 5 A 65MHz 1.4 W Surface Mount DPAK

Tel: +00 852-30501935

RFQ Email: Info@DiGi-Electronics.com

Purchase and inquiry

Manufacturer Product Number:	Manufacturer:
MJD210RLG	onsemi
Series:	Product Status:
-	Active
Transistor Type:	Current - Collector (Ic) (Max):
PNP	5 A
Voltage - Collector Emitter Breakdown (Max):	Vce Saturation (Max) @ Ib, Ic:
25 V	1.8V @ 1A, 5A
Current - Collector Cutoff (Max):	DC Current Gain (hFE) (Min) @ Ic, Vce:
100nA (ICBO)	45 @ 2A, 1V
Power - Max:	Frequency - Transition:
1.4 W	65MHz
Operating Temperature:	Mounting Type:
-65°C ~ 150°C (TJ)	Surface Mount
Package / Case:	Supplier Device Package:
TO-252-3, DPAK (2 Leads + Tab), SC-63	DPAK
Base Product Number:	
MJD210	

Environmental & Export classification

RoHS Status:	Moisture Sensitivity Level (MSL):
ROHS3 Compliant	1 (Unlimited)
REACH Status:	ECCN:
REACH Unaffected	EAR99
HTSUS:	
8541.29.0075	

Complementary Plastic Power Transistors

NPN/PNP Silicon DPAK For Surface Mount Applications

MJD200 (NPN), MJD210 (PNP)

Designed for low voltage, low−power, high−gain audio amplifier applications.

Features

- High DC Current Gain
- Lead Formed for Surface Mount Applications in Plastic Sleeves (No Suffix)
- Low Collector−Emitter Saturation Voltage
- High Current−Gain − Bandwidth Product
- Annular Construction for Low Leakage
- Epoxy Meets UL 94 V−0 @ 0.125 in
- NJV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC−Q101 Qualified and PPAP Capable
- These Devices are Pb−Free and are RoHS Compliant

MAXIMUM RATINGS

Rating	Symbol	Max	Unit
Collector−Base Voltage	V_{CB}	40	Vdc
Collector−Emitter Voltage	V_{CEO}	25	Vdc
Emitter−Base Voltage	V_{EB}	8.0	Vdc
Collector Current − Continuous	I_C	5.0	Adc
Collector Current − Peak	I_{CM}	10	Adc
Base Current	I_B	1.0	Adc
Total Power Dissipation @ T_C = 25°C Derate above 25°C	P_D	 12.5 0.1	 W W/°C
Total Power Dissipation (Note 1) @ T_A = 25°C Derate above 25°C	P_D	 1.4 0.011	 W W/°C
Operating and Storage Junction Temperature Range	T_J, T_{stg}	−65 to +150	°C
ESD − Human Body Model	HBM	3B	V
ESD − Machine Model	MM	C	V

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. These ratings are applicable when surface mounted on the minimum pad sizes recommended.

THERMAL CHARACTERISTICS

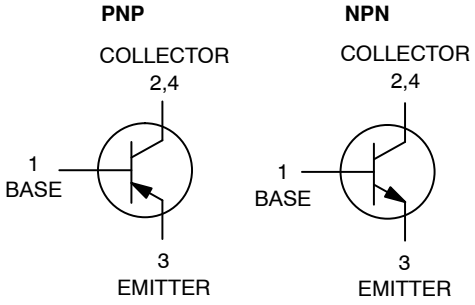
Characteristic	Symbol	Max	Unit
Thermal Resistance, Junction−to−Case	$R_{\theta JC}$	10	°C/W
Thermal Resistance, Junction−to−Ambient (Note 2)	$R_{\theta JA}$	89.3	°C/W

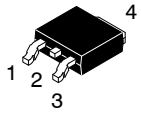
2. These ratings are applicable when surface mounted on the minimum pad sizes recommended.

ON Semiconductor®

www.onsemi.com

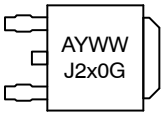
SILICON POWER TRANSISTORS 5 AMPERES 25 VOLTS, 12.5 WATTS





DPAK
CASE 369C
STYLE 1

MARKING DIAGRAM



A = Assembly Location
Y = Year
WW = Work Week
x = 1 or 0
G = Pb−Free Package

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 6 of this data sheet.

MJD200 (NPN), MJD210 (PNP)

ELECTRICAL CHARACTERISTICS (T_C = 25°C unless otherwise noted)

Characteristic	Symbol	Min	Max	Unit
OFF CHARACTERISTICS				
Collector−Emitter Sustaining Voltage (Note 3) (I_C = 10 mAdc, I_B = 0)	$V_{CEO(sus)}$	25	–	Vdc
Collector Cutoff Current (V_{CB} = 40 Vdc, I_E = 0) (V_{CB} = 40 Vdc, I_E = 0, T_J = 125°C)	I_{CBO}	– –	100 100	nAdc μAdc
Emitter Cutoff Current (V_{BE} = 8 Vdc, I_C = 0)	I_{EBO}	–	100	nAdc
ON CHARACTERISTICS				
C Current Gain (Note 3), (I_C = 500 mAdc, V_{CE} = 1 Vdc) (I_C = 2 Adc, V_{CE} = 1 Vdc) (I_C = 5 Adc, V_{CE} = 2 Vdc)	h_{FE}	70 45 10	– 180 –	–
Collector−Emitter Saturation Voltage (Note 3) (I_C = 500 mAdc, I_B = 50 mAdc) (I_C = 2 Adc, I_B = 200 mAdc) (I_C = 5 Adc, I_B = 1 Adc)	$V_{CE(sat)}$	– – –	0.3 0.75 1.8	Vdc
Base−Emitter Saturation Voltage (Note 3) (I_C = 5 Adc, I_B = 1 Adc)	$V_{BE(sat)}$	–	2.5	Vdc
Base−Emitter On Voltage (Note 3) (I_C = 2 Adc, V_{CE} = 1 Vdc)	$V_{BE(on)}$	–	1.6	Vdc
DYNAMIC CHARACTERISTICS				
Current−Gain − Bandwidth Product (Note 4) (I_C = 100 mAdc, V_{CE} = 10 Vdc, f_{test} = 10 MHz)	f_T	65	–	MHz
Output Capacitance (V_{CB} = 10 Vdc, I_E = 0, f = 0.1 MHz) MJD200 MJD210, NJVMJD210T4G	C_{ob}	– –	80 120	pF

3. Pulse Test: Pulse Width = 300 μs, Duty Cycle ≈ 2%.
4. $f_T = |h_{fe}| \bullet f_{test}$.

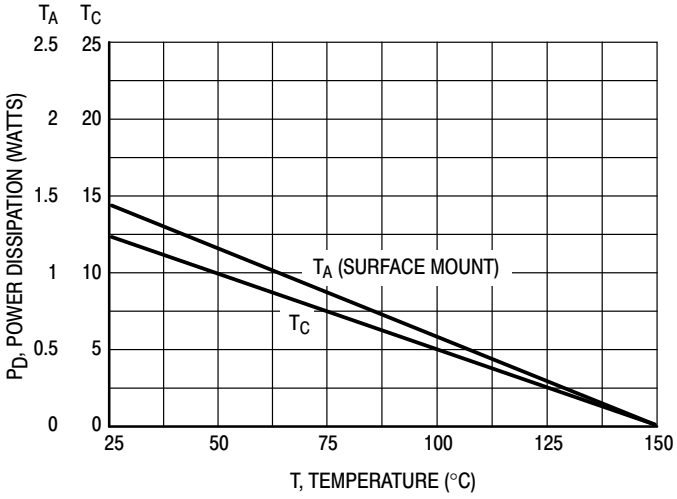


Figure 1. Power Derating

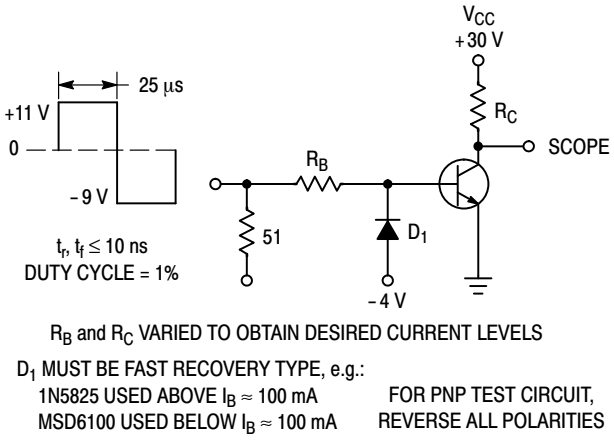


Figure 2. Switching Time Test Circuit

MJD200 (NPN), MJD210 (PNP)

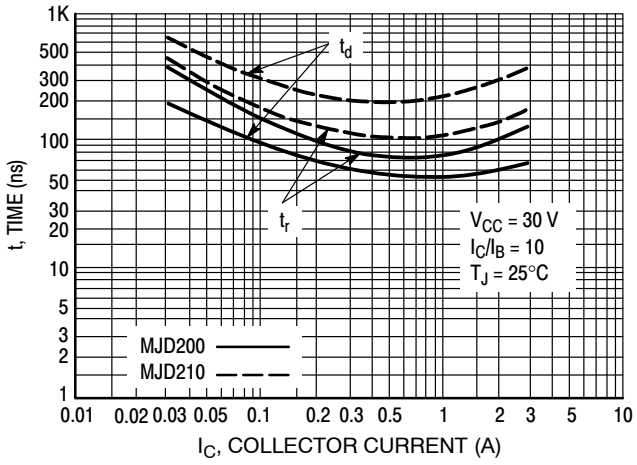


Figure 3. Turn−On Time

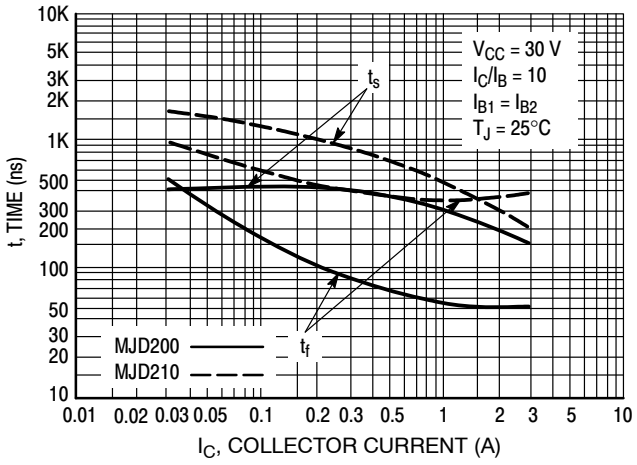
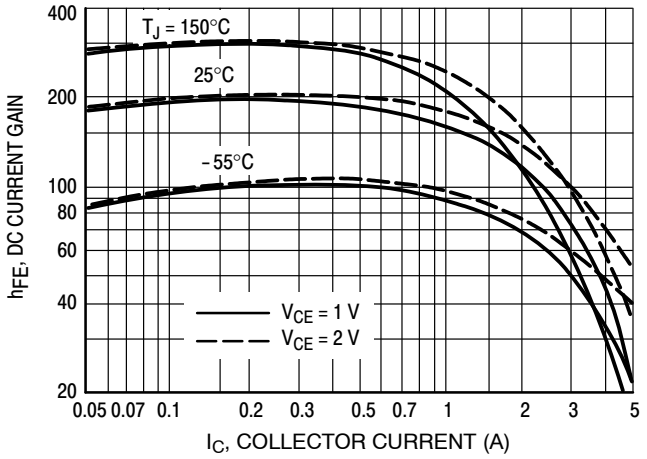


Figure 4. Turn−Off Time

MJD200 (NPN), MJD210 (PNP)

NPN
MJD200



PNP
MJD210

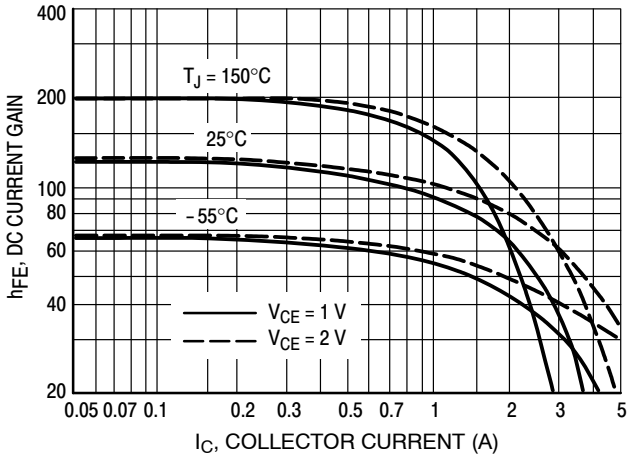
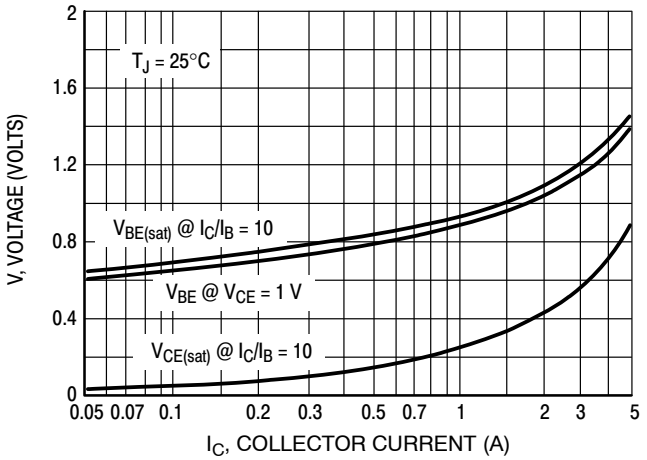


Figure 5. DC Current Gain



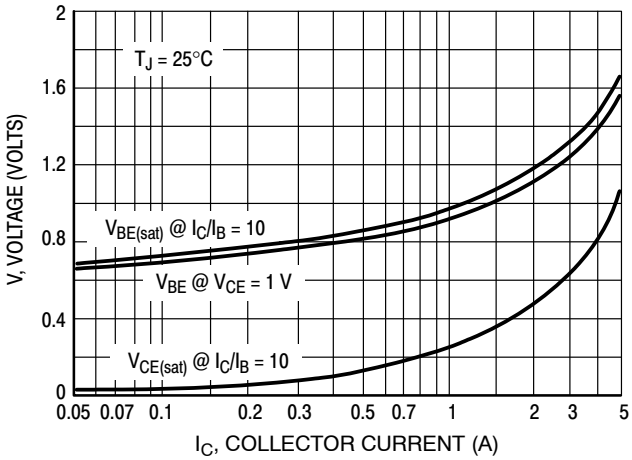
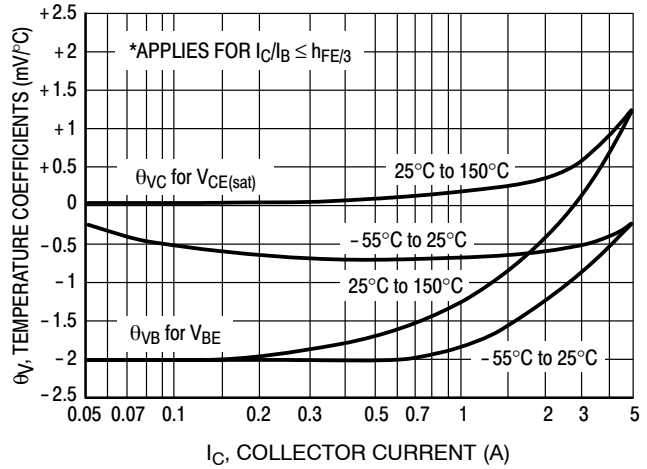


Figure 6. “On” Voltage



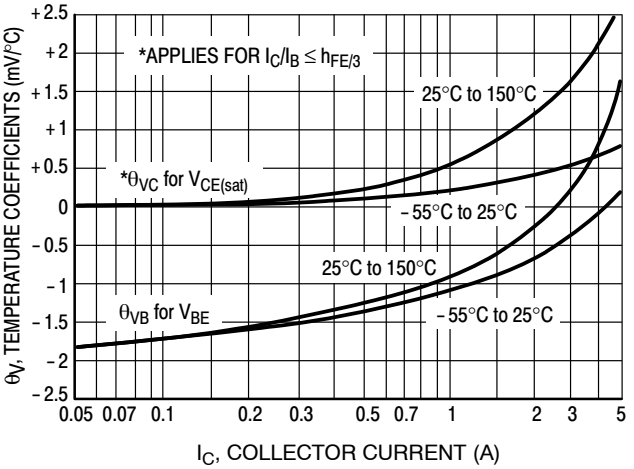


Figure 7. Temperature Coefficients

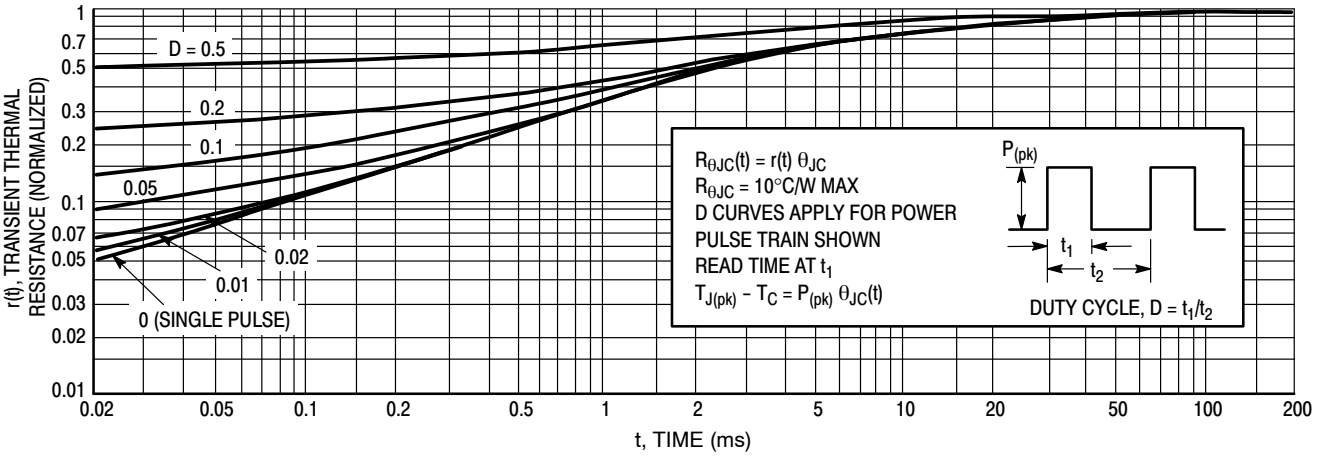


Figure 8. Thermal Response

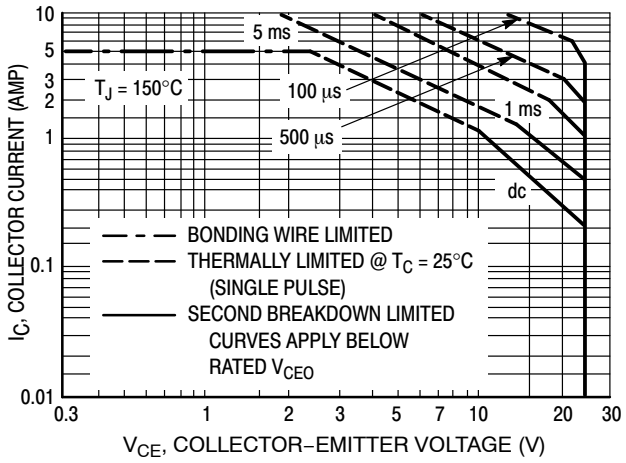


Figure 9. Active Region Safe Operating Area

There are two limitations on the power handling ability of a transistor: average junction temperature and second breakdown. Safe operating area curves indicate $I_C - V_{CE}$ limits of the transistor that must be observed for reliable operation; i.e., the transistor must not be subjected to greater dissipation than the curves indicate.

The data of Figure 9 is based on $T_{J(pk)}$ = 150°C; T_C is variable depending on conditions. Second breakdown pulse limits are valid for duty cycles to 10% provided $T_{J(pk)} \leq 150°C$. $T_{J(pk)}$ may be calculated from the data in Figure 8. At high case temperatures, thermal limitations will reduce the power that can be handled to values less than the limitations imposed by second breakdown.

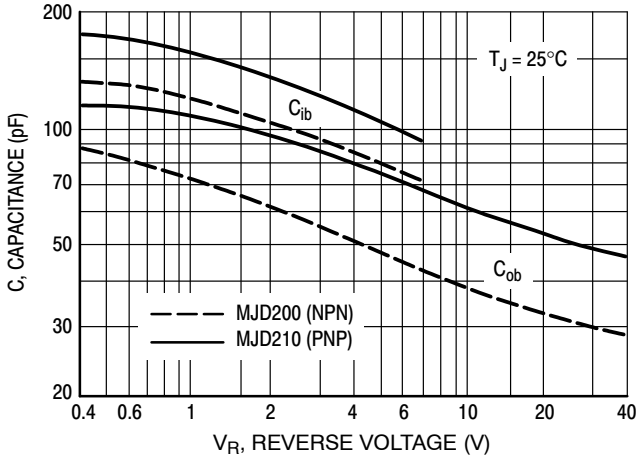


Figure 10. Capacitance

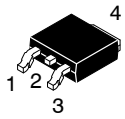
ORDERING INFORMATION

Device	Package Type	Shipping†
MJD200G	DPAK (Pb−Free)	75 Units / Rail
MJD200RLG	DPAK (Pb−Free)	1,800 / Tape & Reel
MJD200T4G	DPAK (Pb−Free)	2,500 / Tape & Reel
MJD210G	DPAK (Pb−Free)	75 Units / Rail
MJD210RLG	DPAK (Pb−Free)	1,800 / Tape & Reel
MJD210T4G	DPAK (Pb−Free)	2,500 / Tape & Reel
NJVMJD210T4G*	DPAK (Pb−Free)	2,500 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

*NJV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC−Q101 Qualified and PPAP Capable

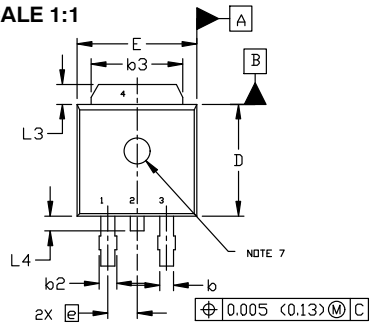
MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS



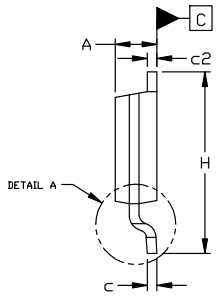
DPAK (SINGLE GAUGE)
CASE 369C
ISSUE G

DATE 31 MAY 2023

SCALE 1:1



TOP VIEW

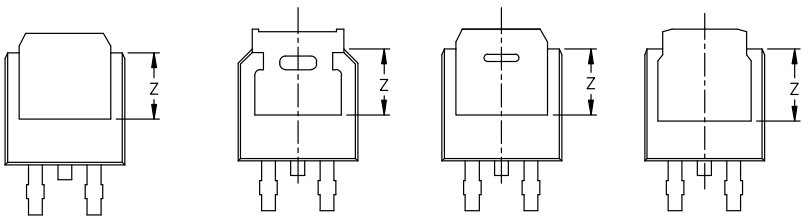


SIDE VIEW

NOTES:

1. DIMENSIONING AND TOLERANCING ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: INCHES
3. THERMAL PAD CONTOUR OPTIONAL WITHIN DIMENSIONS b3, L3, AND Z.
4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR BURRS. MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.006 INCHES PER SIDE.
5. DIMENSIONS D AND E ARE DETERMINED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY.
6. DATUMS A AND B ARE DETERMINED AT DATUM PLANE H.
7. OPTIONAL MOLD FEATURE.

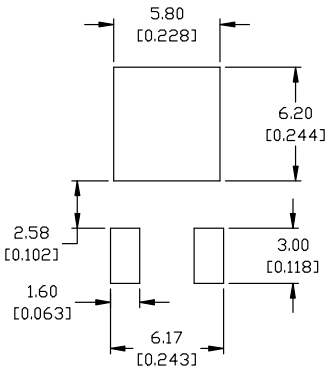
DIM	INCHES		MILLIMETERS	
	MIN.	MAX.	MIN.	MAX.
A	0.086	0.094	2.18	2.38
A1	0.000	0.005	0.00	0.13
b	0.025	0.035	0.63	0.89
b2	0.028	0.045	0.72	1.14
b3	0.180	0.215	4.57	5.46
c	0.018	0.024	0.46	0.61
c2	0.018	0.024	0.46	0.61
D	0.235	0.245	5.97	6.22
E	0.250	0.265	6.35	6.73
e	0.090 BSC		2.29 BSC	
H	0.370	0.410	9.40	10.41
L	0.055	0.070	1.40	1.78
L1	0.114 REF		2.90 REF	
L2	0.020 BSC		0.51 BSC	
L3	0.035	0.050	0.89	1.27
L4	----	0.040	---	1.01
Z	0.155	----	3.93	---



BOTTOM VIEW

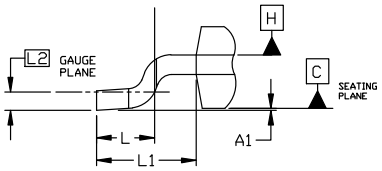
BOTTOM VIEW

ALTERNATE CONSTRUCTIONS



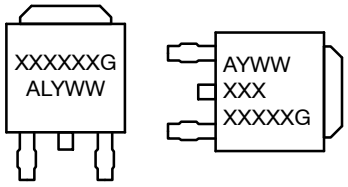
RECOMMENDED MOUNTING FOOTPRINT*

*FOR ADDITIONAL INFORMATION ON OUR PB-FREE STRATEGY AND SOLDERING DETAILS, PLEASE DOWNLOAD THE ON SEMICONDUCTOR SOLDERING AND MOUNTING TECHNIQUES REFERENCE MANUAL, SOLDERRM/D.



DETAIL A
ROTATED 90° CW

GENERIC MARKING DIAGRAM*



IC **Discrete**

XXXXXX = Device Code
A = Assembly Location
L = Wafer Lot
Y = Year
WW = Work Week
G = Pb−Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb−Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.

STYLE 1:
PIN 1. BASE
2. COLLECTOR
3. EMITTER
4. COLLECTOR

STYLE 2:
PIN 1. GATE
2. DRAIN
3. SOURCE
4. DRAIN

STYLE 3:
PIN 1. ANODE
2. CATHODE
3. ANODE
4. CATHODE

STYLE 4:
PIN 1. CATHODE
2. ANODE
3. GATE
4. ANODE

STYLE 5:
PIN 1. GATE
2. ANODE
3. CATHODE
4. ANODE

STYLE 6:
PIN 1. MT1
2. MT2
3. GATE
4. MT2

STYLE 7:
PIN 1. GATE
2. COLLECTOR
3. EMITTER
4. COLLECTOR

STYLE 8:
PIN 1. N/C
2. CATHODE
3. ANODE
4. CATHODE

STYLE 9:
PIN 1. ANODE
2. CATHODE
3. RESISTOR ADJUST
4. CATHODE

STYLE 10:
PIN 1. CATHODE
2. ANODE
3. CATHODE
4. ANODE

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DESCRIPTION:	**DPAK (SINGLE GAUGE)**	**PAGE 1 OF 1**

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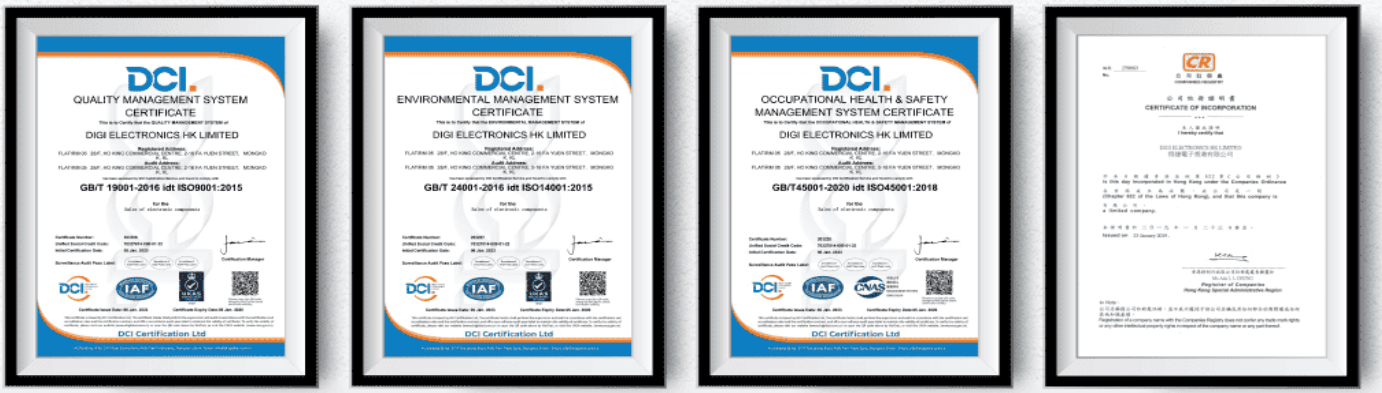
OUR CERTIFICATE

DiGi provide top-quality products and perfect service for customer worldwide through standardization, technological innovation and continuous improvement. DiGi through third-party certification, we striciy control the quality of products and services. Welcome your RFQ to Email: Info@DiGi-Electronics.com



Tel: +00 852-30501935

RFQ Email: Info@DiGi-Electronics.com

DiGi is a global authorized distributor of electronic components.